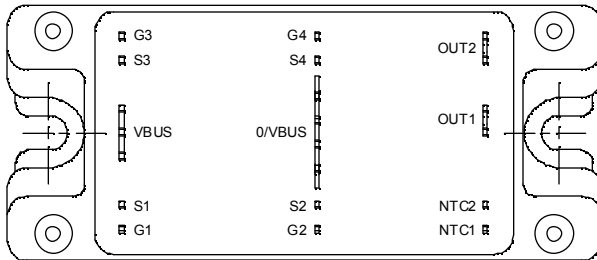
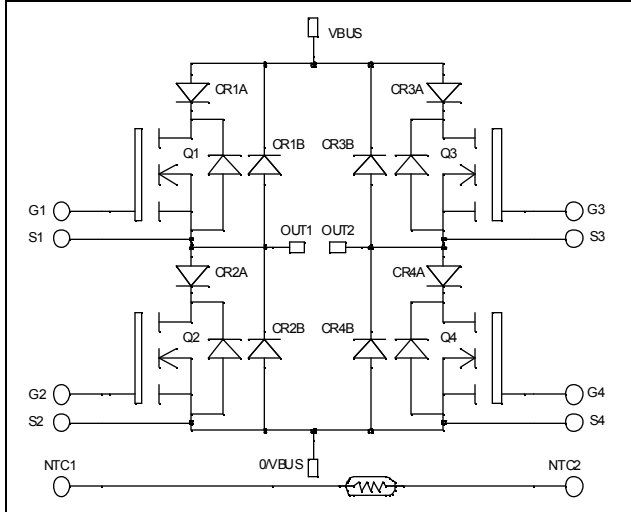


**Full - Bridge
Series & SiC parallel diodes
Super Junction
MOSFET Power Module**



Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	600	V
I_D	Continuous Drain Current	$T_c = 25^\circ\text{C}$ 39	A
		$T_c = 80^\circ\text{C}$ 29	
I_{DM}	Pulsed Drain current	160	
V_{GS}	Gate - Source Voltage	± 20	V
$R_{DS(on)}$	Drain - Source ON Resistance	70	m Ω
P_D	Maximum Power Dissipation	$T_c = 25^\circ\text{C}$ 250	W
I_{AR}	Avalanche current (repetitive and non repetitive)	20	A
E_{AR}	Repetitive Avalanche Energy	1	mJ
E_{AS}	Single Pulse Avalanche Energy	1800	



CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

Application

- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- **COOLMOS**
Power Semiconductors
 - Ultra low $R_{DS(on)}$
 - Low Miller capacitance
 - Ultra low gate charge
 - Avalanche energy rated
- **Parallel SiC Schottky Diode**
 - Zero reverse recovery
 - Zero forward recovery
 - Temperature Independent switching behavior
 - Positive temperature coefficient on VF
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS compliant

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 600V, T_j = 25^\circ\text{C}$			25	μA
		$V_{GS} = 0V, V_{DS} = 600V, T_j = 125^\circ\text{C}$			250	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 39A$			70	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.7\text{mA}$	2.1	3	3.9	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$		7		nF
C_{oss}	Output Capacitance	$V_{DS} = 25V$		2.56		
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		0.21		
Q_g	Total gate Charge	$V_{GS} = 10V$		259		nC
Q_{gs}	Gate – Source Charge	$V_{Bus} = 300V$		29		
Q_{gd}	Gate – Drain Charge	$I_D = 39A$		111		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 400V$ $I_D = 39A$ $R_G = 5\Omega$		21		ns
T_r	Rise Time			30		
$T_{d(off)}$	Turn-off Delay Time			283		
T_f	Fall Time			84		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 15V, V_{Bus} = 400V$ $I_D = 39A, R_G = 5\Omega$		402		μJ
E_{off}	Turn-off Switching Energy			980		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 400V$ $I_D = 39A, R_G = 5\Omega$		658		μJ
E_{off}	Turn-off Switching Energy			1206		

Series diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		200			V
I_{RM}	Maximum Reverse Leakage Current	$V_R = 200V$	$T_j = 25^\circ\text{C}$		250	μA
			$T_j = 125^\circ\text{C}$		500	
I_F	DC Forward Current	$T_c = 85^\circ\text{C}$		30		A
V_F	Diode Forward Voltage	$I_F = 30A$		1.1	1.15	V
		$I_F = 60A$		1.4		
		$I_F = 30A, T_j = 125^\circ\text{C}$		0.9		
t_{rr}	Reverse Recovery Time	$I_F = 30A$ $V_R = 133V$ $di/dt = 200A/\mu\text{s}$	$T_j = 25^\circ\text{C}$	24		ns
			$T_j = 125^\circ\text{C}$	48		
Q_{rr}	Reverse Recovery Charge	$T_j = 25^\circ\text{C}$		33		nC
			$T_j = 125^\circ\text{C}$	150		

Parallel diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V _{RRM}	Maximum Peak Repetitive Reverse Voltage			600			V
I _{RM}	Maximum Reverse Leakage Current	V _R =600V	T _j = 25°C		100	400	μA
			T _j = 175°C		200	2000	
I _F	DC Forward Current		T _c = 125°C		20		A
V _F	Diode Forward Voltage	I _F = 20 A	T _j = 25°C		1.6	1.8	V
			T _j = 175°C		2.0	2.4	
Q _C	Total Capacitive Charge	I _F = 20 A, V _R = 300 V di/dt = 800 A/μs			28		nC
C	Total Capacitance	f = 1 MHz, V _R = 200 V			130		pF
		f = 1 MHz, V _R = 400 V			100		

Thermal and package characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
R _{thJC}	Junction to Case Thermal Resistance	Transistor				0.5	°C/W
		Series diode				1.2	
		Parallel diode				1.5	
V _{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, I _{isol} < 1 mA, 50/60 Hz			2500			V
T _J	Operating junction temperature range			-40		150	°C
T _{STG}	Storage Temperature Range			-40		125	
T _C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To Heatsink	M5	2.5		4.7	N.m
Wt	Package Weight					160	g

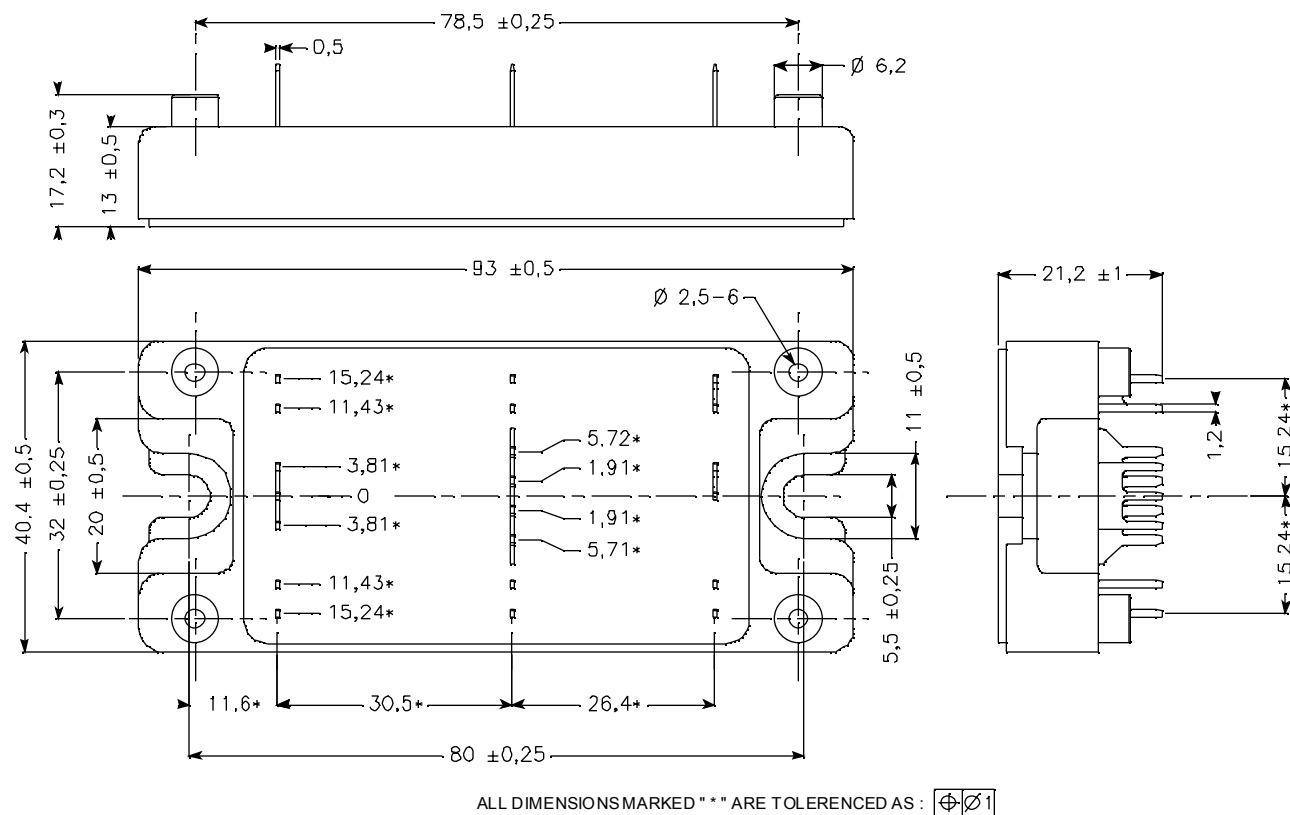
Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
B _{25/85}	T ₂₅ = 298.15 K		3952		K

$$R_T = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

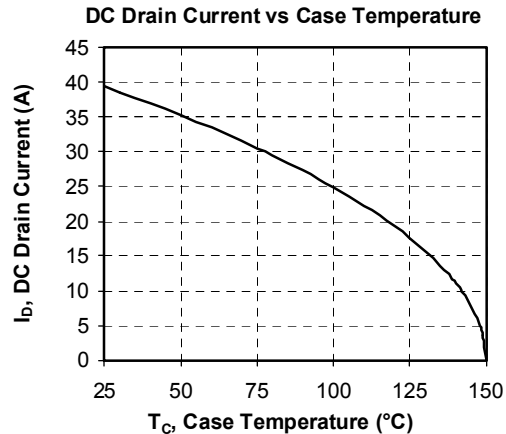
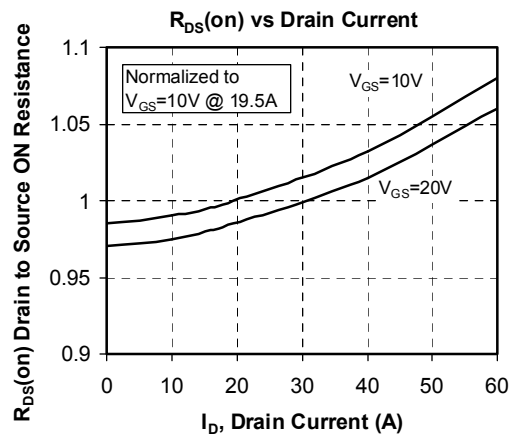
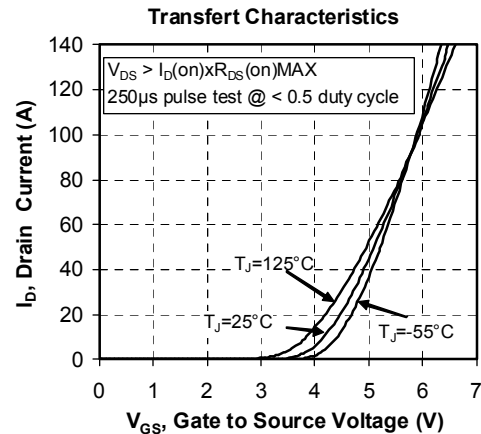
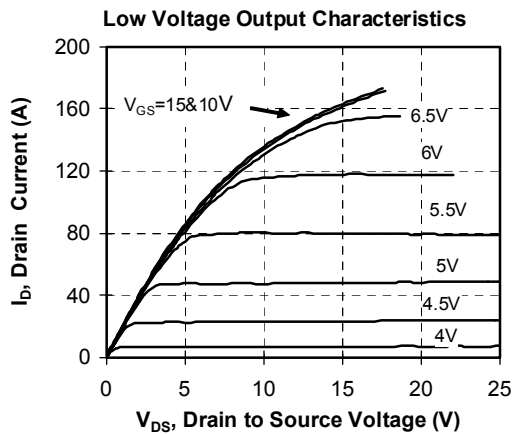
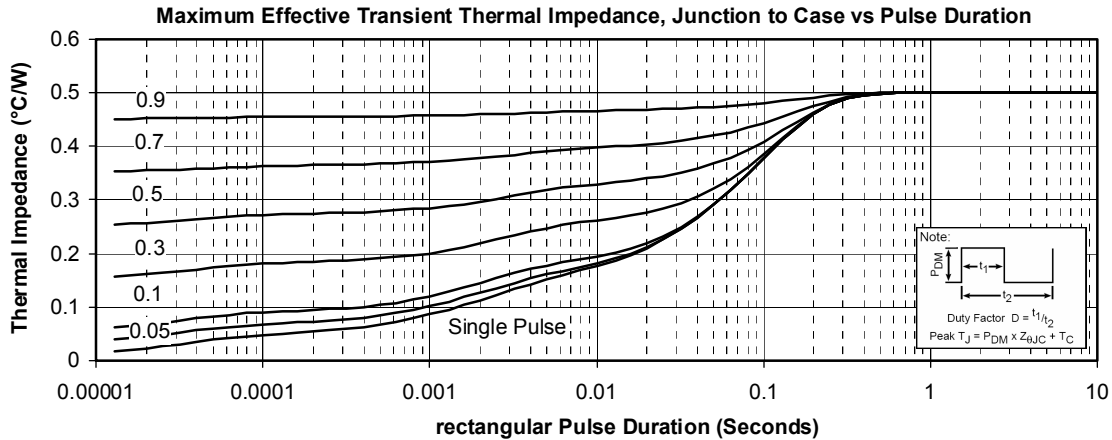
T: Thermistor temperature
R_T: Thermistor value at T

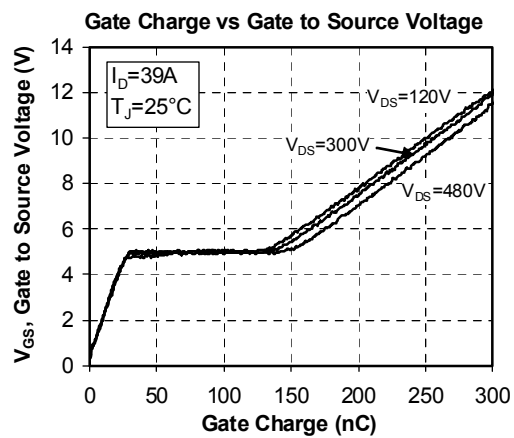
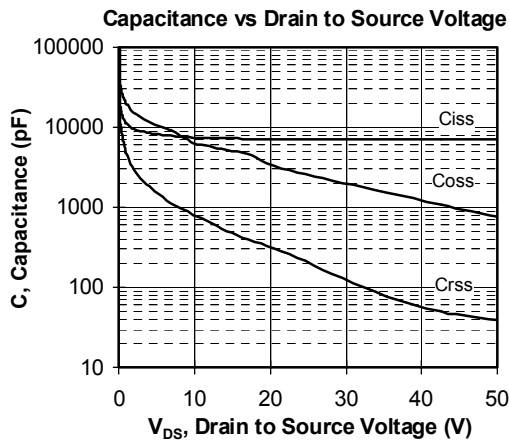
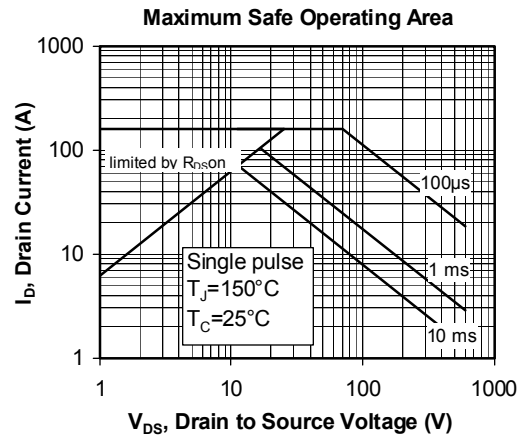
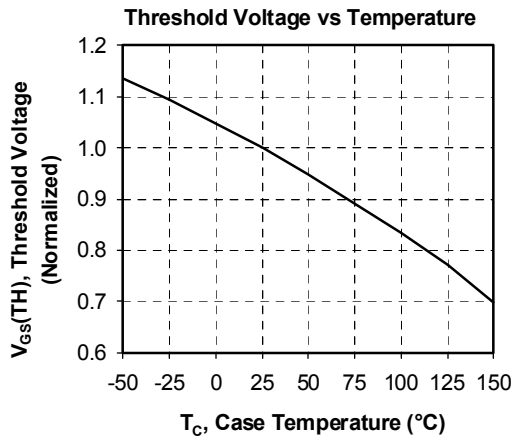
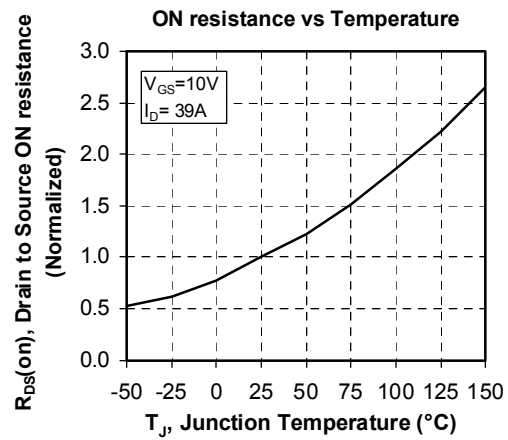
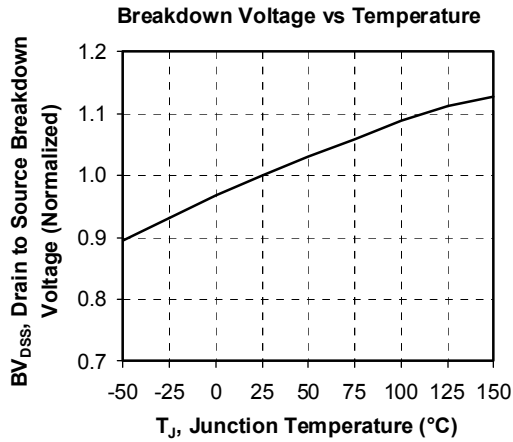
SP4 Package outline (dimensions in mm)

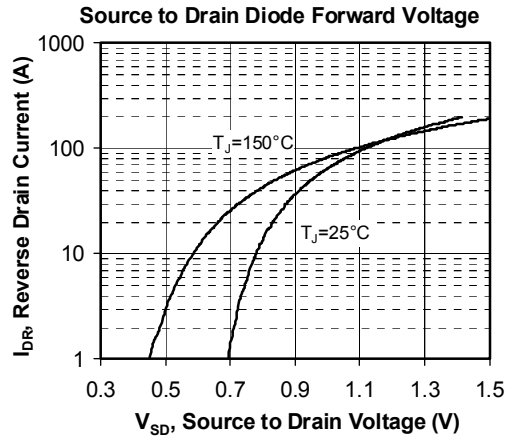
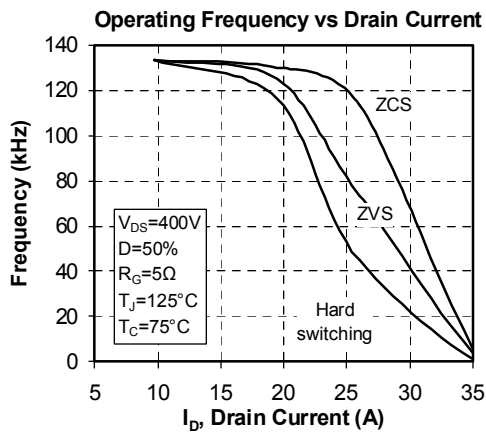
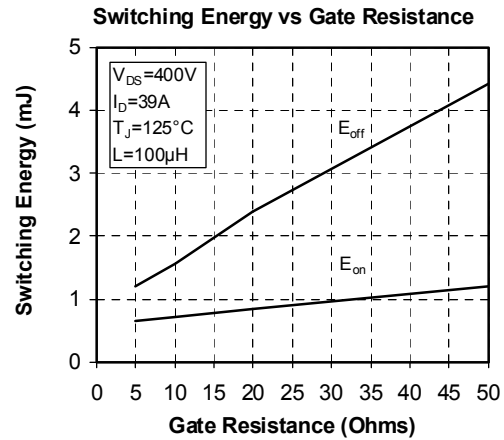
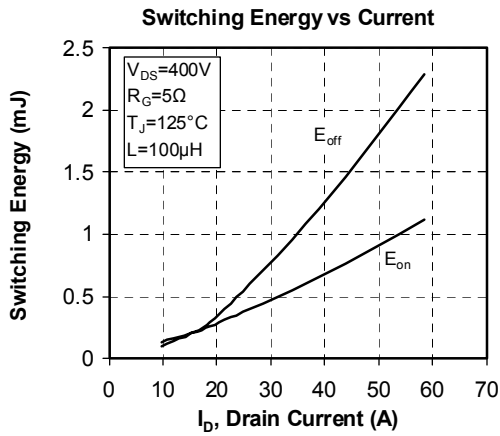
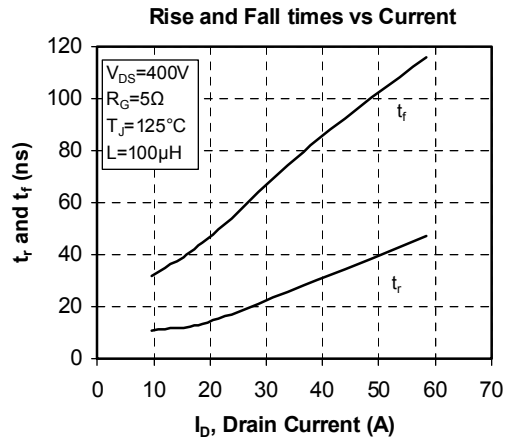
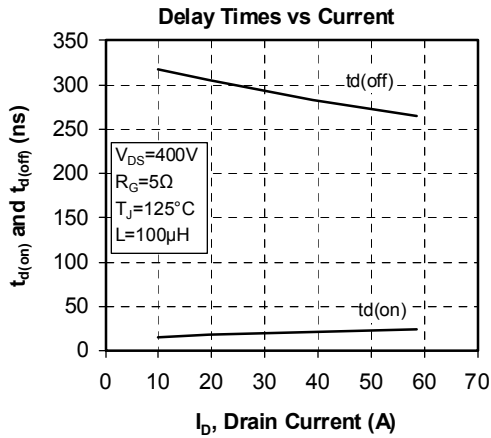


See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

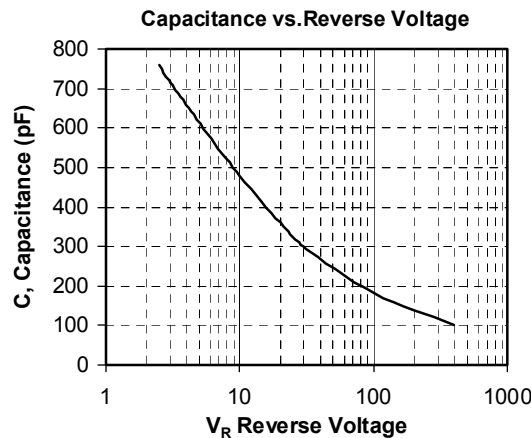
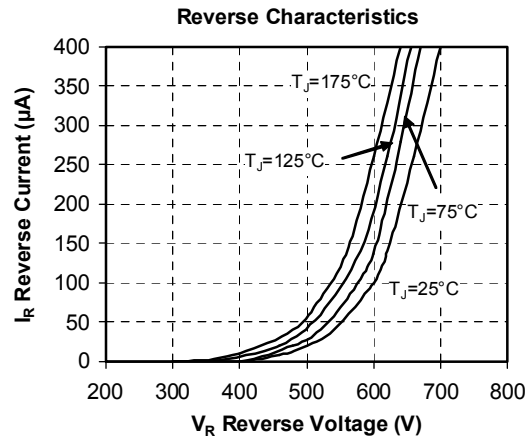
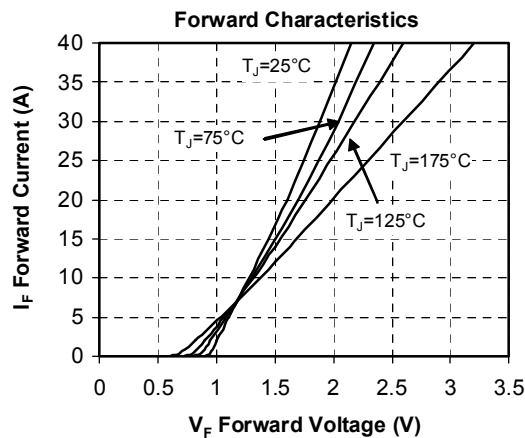
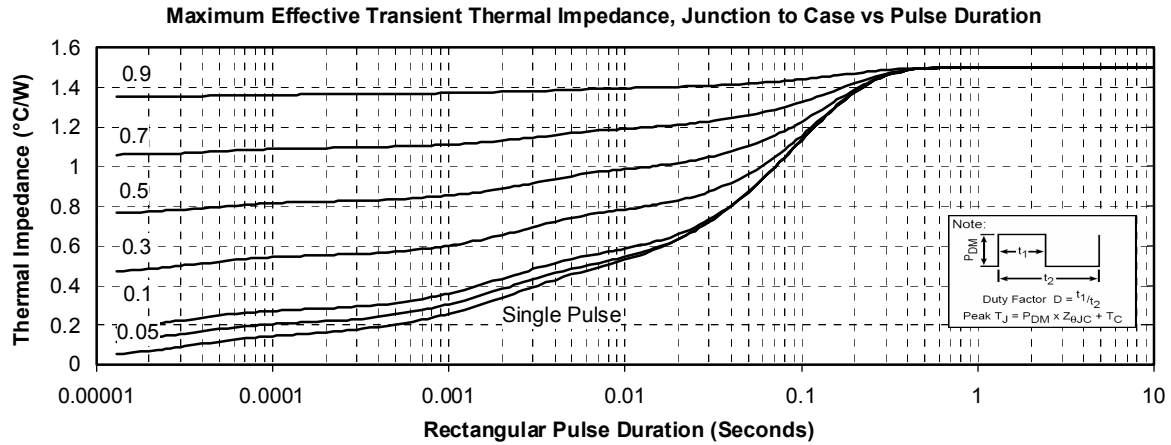
Typical CoolMOS Performance Curve







Typical SiC Diode Performance Curve



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